# PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
SUNGKYU KANG	01/27/2021
JONGWAN CHOI	01/27/2021
YOUNGHOON KIM	01/27/2021
HIECHUL KIM	01/27/2021
KYUNGEUN LEE	01/27/2021
TAEHEE YOO	01/27/2021

#### **RECEIVING PARTY DATA**

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Street Address:	VERSTERKERSTRAAT 8	
City:	ALMERE	
State/Country:	NETHERLANDS	
Postal Code:	1322 AP	

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17217514

## **CORRESPONDENCE DATA**

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TTORNEY DOCKET NUMBER: PAT-KOR-0153-US-NP	
NAME OF SUBMITTER: MICHELLE SYMPSON	
SIGNATURE: /Michelle Sympson/	
DATE SIGNED:	04/08/2021

**Total Attachments: 3** 

PATENT REEL: 055862 FRAME: 0380 source=PAT-KOR-0153-US-NP Assignment Executed#page1.tif source=PAT-KOR-0153-US-NP Assignment Executed#page2.tif source=PAT-KOR-0153-US-NP Assignment Executed#page3.tif

PATENT REEL: 055862 FRAME: 0381 Application Serial No.: 17/217,514 Docket No.: PAT-KOR-0153-US-NP

Filing Date: March 30, 2021

Title: THIN FILM FORMING METHOD

## **ASSIGNMENT**

WHEREAS, SungKyu KANG, a citizen of the Republic of Korea and a resident of Hwaseong-si, Gyeonggi-do, Republic of Korea; JongWan CHOI, a citizen of the Republic of Korea and a resident of Hwaseong-si, Gyeonggi-do, Republic of Korea; YoungHoon KIM, a citizen of the Republic of Korea and a resident of Cheonan-si, Chungcheongnam-do, Republic of Korea; HieChul KIM, a citizen of Republic of Korea and a resident of Hwaseong-si, Gyeonggi-do, Republic of Korea; KyungEun LEE, a citizen of Republic of Korea and a resident of Suwon-si, Gyeonggi-do, Republic of Korea; and TaeHee YOO, a citizen of Republic of Korea and a resident of Bucheon-si, Gyeonggi-do, Republic of Korea,

(collectively, "WE" or "ASSIGNOR") have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to THIN FILM FORMING METHOD (collectively, the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefore; and

WHEREAS, ASM IP HOLDING B.V. (hereinafter "ASSIGNEE"), a corporation having a place of business at Versterkerstraat 8, Almere, 1322 AP, Netherlands, desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all patent applications therefore, and all patents that have granted or may be granted hereafter thereon, including, but not limited to, those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed and transferred, and by these presents do hereby sell, assign, convey and transfer, unto ASSIGNEE, its successors, its legal representatives and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefore that may have been filed or may be filed hereafter for said INVENTIONS (including but not limited Application No(s). 17/217,514, filed on March 30, 2021, as Docket No. PAT-KOR-0153-US-NP (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known)) and all rights of priority under International Conventions, Treaties, and Agreements, all utility applications, national phase applications, utility model applications, divisional applications, renewal applications, continuation applications, validation applications and design applications thereof, and all issued patents which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon;

Application Serial No.:  Filing Date:  Title: THIN FILM FORMING METHOD	Docket No.: PAT-KOR-0153-US-NP
it is to issue patents on applications or regis	nest any Official of any country or countries whose duty strations, to issue all patents for said INVENTIONS to entatives, and its assigns, in accordance with the terms
legal representatives, and its assigns all cl relating to any violation(s) of any of the ri prior to the date of assignment to said AS limited to the right to sue for, seek, obtain,	fer, and convey to said ASSIGNEE, its successors, its laims for damages and all remedies arising out of or ights assigned hereby that have or may have accrued SIGNEE, or may accrue hereafter, including, but not collect, recover and retain damages and any ongoing be entitled, or form any settlement or agreement related ce;
its successors, its legal representatives, an INVENTIONS, and will testify in any le applications and certificates, make all right	at WE will communicate promptly to said ASSIGNEE, and its assigns, any facts known to us respecting said egal proceeding, sign all lawful papers, execute all tful declarations and/or oaths, and provide all lawful ers, its legal representatives, and its assigns, to obtain ENTIONS in all countries.
EXECUTED as of the date(s) below by ASS	SIGNOR:
SungKyu KANG/	
James Colomon	2021-1.211
Signature	Date
Jong Wan CHOI	
Signature 2	<u> 201, 1,2り</u> Date
YoungHoon KIM	Lyane
1 Congricon Kilvi	2021. 1.27
Signature	Date
HieChul KIM	

Page 2 of 3

Date

Signature

Filing Date: Title: THIN FILM FORMING MET	Docket No.: PAT-KOR-0153-US-NI
KyungEun LEE	202(, /, 29
Signature	Date
TaeHee YOO	204. (, 21
Signature	Date

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